

VERSION WITH MARKINGS TO SHOW CHANGES MADE TO SPECIFICATION

Paragraph beginning at page 14, line 13:

The substrate 1 may be made of glass-fiber-reinforced epoxy resin for example and has a rectangular or strip-like configuration elongated in one direction. The substrate 1 is formed with a plurality of slits 18 spaced from each other longitudinally of the substrate 1. Each of the slits 18 is narrow and extends widthwise of the substrate 1. The substrate [10] 1 has an obverse surface 10a which provides component mounting regions S each between respective two adjacent slits 18 for mounting components, as described later. Each of the component mounting regions S includes a plurality of sub-areas 19 and a conductor layer 10 surrounding each of the sub-areas 19.

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1. (Amended) A method of making infrared data communication modules comprising the steps of:

forming predetermined [wiring] conductor patterns on an obverse and a reverse surfaces of a substrate;

mounting, on one of the surfaces of the substrate, [a group of components including] plural sets of light emitting elements and light receiving elements;

[resin-packaging the group of components mounted] resin-molding an initial package which encloses the plural sets of light emitting elements and light receiving elements on the substrate; and

dividing [the resin-packaged components into a plurality of infrared data communication modules] the initial package into a plurality of final packages each of which [includes] encloses a respective set of light emitting element and light receiving element;

[wherein the resin-packaging step comprises forming a plurality of mutually separated resin packages each of which collectively seals at least two sets of light emitting elements and light receiving elements.]

wherein the mounting step includes arranging the plural sets of light emitting elements and light receiving elements in a matrix on said one surface of the substrate; and

wherein the resin-molding step includes forming a plurality of initial packages arranged in a matrix.

3. (Amended) The method of making infrared data communication modules according to claim [1] 2, wherein the substrate is elongated in one direction, [to be rectangular or strip-like,] the substrate being formed with a plurality of slits extending widthwise of the substrate and spaced from each other longitudinally of the substrate, [the group of components] the plural sets of light emitting elements and light receiving elements being mounted on said one surface of the substrate in each of regions defined between the slits.